



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Toshifumi KIMBA et al.

Serial No. 09/734,737

Filed December 13, 2000

Confirmation No. 4508

Docket No. 2000-1706A

Group Art Unit 2877

Examiner Hoa Q. Pham

SUBSTRATE FILM THICKNESS
MEASUREMENT METHOD, SUBSTRATE
FILM THICKNESS MEASUREMENT
APPARATUS AND SUBSTRATE
PROCESSING APPARATUS

ELECTION OF INVENTION

Assistant Commissioner for Patents,
Washington, D.C.

Sir:

In response to the restriction requirement of January 15, 2003, Applicants in the above-referenced U.S. patent application hereby elect the invention of group I, corresponding to claims 1-18.

An early and favorable action on the merits is earnestly solicited.

Respectfully submitted,

Toshifumi KIMBA et al.

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February 11, 2003

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